

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

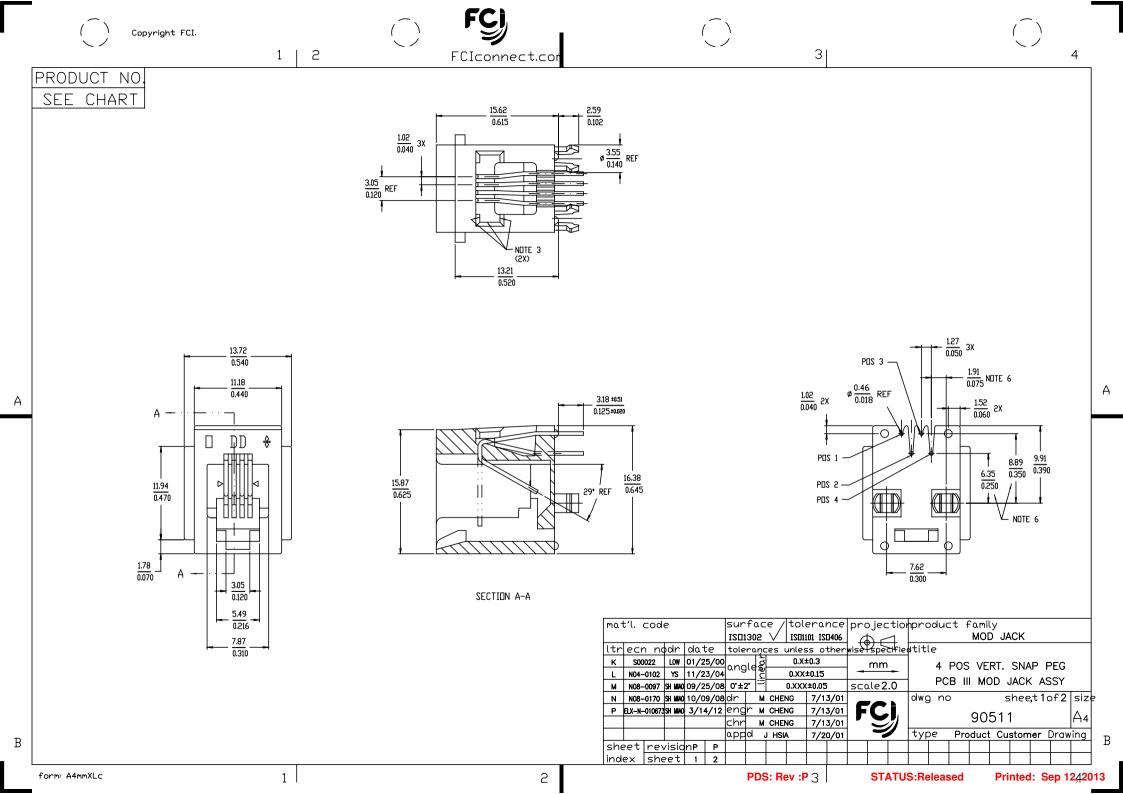
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









FCIconnect.com

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CONTACT PLATING

5u" Au + high performance lubricant

5u" Au + high performance lubricant

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REMARKS

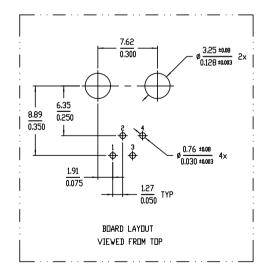
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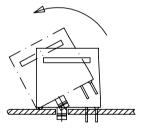
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	PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	NOTES	
Ī	90511-001 -001LF -001HLF	ALL	5u" Au + high performance lubricant	BLACK	
	-002 -002LF -002HLF	ALL	5u" Au + high performance lubricant	BLACK	11)
	-003 -003LF	ALL	5u" Au + high performance lubricant	GREY	
	-004 -004LF	ALL	5u" Au + high performance lubricant	GREY	(11)
	-005 -005LF -005HLF	ALL	50u″ / 1.27u GXT	BLACK	

1 | 2

LEAD FREE PRODUCT NO. - MEETS PIP PROCESS PRODUCT NO.



DIRECTION OF DISMOUNT



JACK DISMOUNT METHOD DETAIL A NDTE 5

NOTES :

POSITIONS

LOADED

ALL

ALL

PRODUCT NO.

90511-101 -101LF

> -101HLF -102 -102LF

-102HLF

- P/ND WITH DASH OXX -NDRMAL WAVE SOLDERING APPLICATION. P/ND WITH DASH 1XX -1R REFLOW APPLICATION (NOT TODLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57/,062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN, (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED. OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS AU AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR

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